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## MAX9275/MAX9279

## 3.12Gbps GMSL Serializers for Coax or STP Output Drive and Parallel Input

### General Description

The MAX9275/MAX9279 are 3.12Gbps Gigabit Multimedia Serial Link (GMSL) serializers with parallel LVCMOS inputs and a CML serial output programmable for 50Ω coax or 100Ω shielded twisted pair (STP) cable drive. The MAX9279 has HDCP content protection but otherwise is the same as the MAX9275. The serializers pair with any GMSL deserializer capable of coax input. When programmed for STP output they are backward compatible with any GMSL deserializer. The output amplitude is programmable 100mV to 500mV, single-ended (coax) or 100mV to 400mV differential (STP).

The audio channel supports L-PCM I<sup>2</sup>S stereo and up to eight channels of L-PCM in TDM mode. Sample rates of 32kHz to 192kHz are supported with sample depth up to 32 bits.

The embedded control channel operates at 9.6kbps to 1Mbps in UART-UART and UART-I<sup>2</sup>C modes, and up to 1Mbps in I<sup>2</sup>C-I<sup>2</sup>C mode. Using the control channel, a μC can program serializer, deserializer, and peripheral device registers at any time, independent of video timing, and manage HDCP operation (MAX9279). A GPO output supports touch-screen controller interrupt requests from the remote end of the link.

For use with longer cables, the serializers have programmable pre/deemphasis. Programmable spread spectrum is available on the serial output. The serial output meets ISO 10605 and IEC 61000-4-2 ESD standards. The core supply is 1.7V to 1.9V and the I/O supply is 1.7V to 3.6V. The MAX9275/MAX9279 are available in a lead-free, 56-pin, 8mm x 8mm, TQFN package with exposed pad and 0.5mm lead pitch.

### Applications

- High-Resolution Automotive Navigation
- Rear-Seat Infotainment
- Megapixel Camera Systems

### Benefits and Features

- Ideal for High-Definition Video Applications
  - Drives Low-Cost 50Ω Coax Cable and FAKRA Connectors or 100Ω STP
  - 104MHz High-Bandwidth Mode Supports 1920x720p/60Hz Display With 24-Bit Color
  - Serializer Pre/Deemphasis Allows 15m Cable at Full Speed
  - Up to 192kHz Sample Rate And 32-Bit Sample Depth For 7.1 Channel HD Audio
- Multiple Data Rates for System Flexibility
  - Up to 3.12Gbps Serial-Bit Rate
  - 6.25MHz to 104MHz Pixel Clock
  - 9.6kbps to 1Mbps Control Channel in UART, Mixed UART/I<sup>2</sup>C, or I<sup>2</sup>C Mode with Clock Stretch Capability
- Reduces EMI and Shielding Requirements
  - Serial Output Programmable for 100mV to 500mV Single-Ended or 100mV to 400mV Differential
  - Programmable Spread Spectrum Reduces EMI
  - Bypassable Input PLL for Parallel Clock Jitter Attenuation
  - Tracks Spread Spectrum on Input
  - High-Immunity Mode for Maximum Control-Channel Noise Rejection
- Peripheral Features for System Power-Up and Verification
  - Built-In PRBS Generator for BER Testing of the Serial Link
  - Dedicated “Up/Down” GPO for Touch-Screen Interrupt and Other Uses
  - Remote/Local Wake-Up from Sleep Mode
- Meets Rigorous Automotive and Industrial Requirements
  - -40°C to +105°C Operating Temperature
  - ±8kV Contact and ±15kV Air ISO 10605 and IEC 61000-4-2 ESD Protection

Ordering Information appears at end of data sheet.

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**Absolute Maximum Ratings (Note 1)**

AVDD to EP.....	-0.5V to +1.9V	Continuous Power Dissipation (T <sub>A</sub> = +70°C)
DVDD to EP.....	-0.5V to +1.9V	TQFN (derate 47.6mW/°C above +70°C).....
IOVDD to EP.....	-0.5V to +3.9V	Junction Temperature.....
LMN_ to EP (15mA current limit).....	-0.5V to +3.9V	Storage Temperature.....
OUT+, OUT- to EP.....	-0.5V to +1.9V	Lead Temperature (soldering, 10s).....
All Other Pins to EP.....	-0.5V to (V <sub>IOVDD</sub> + 0.5V)	Soldering Temperature (reflow).....
OUT+, OUT- Short Circuit to Ground or Supply.....	Continuous	

**Note 1:** EP connected to PCB ground.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Package Thermal Characteristics (Note 2)**

TQFN

Junction-to-Case Thermal Resistance (θ <sub>JC</sub> ).....	1°C/W
Junction-to-Ambient Thermal Resistance (θ <sub>JA</sub> ).....	21°C/W

**Note 2:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to [www.maximintegrated.com/thermal-tutorial](http://www.maximintegrated.com/thermal-tutorial).

**DC Electrical Characteristics**

(V<sub>AVDD</sub> = V<sub>DVDD</sub> = 1.7V to 1.9V, V<sub>IOVDD</sub> = 1.7V to 3.6V, R<sub>L</sub> = 100Ω ±1% (differential), EP connected to PCB ground (GND), T<sub>A</sub> = -40°C to +105°C, unless otherwise noted. Typical values are at V<sub>AVDD</sub> = V<sub>DVDD</sub> = V<sub>IOVDD</sub> = 1.8V, T<sub>A</sub> = +25°C.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
<b>SINGLE-ENDED INPUTS (DIN_, PCLKIN, PWDN, MS/CNTL0, CDS/CNTL3, SD, SCK, WS, HIM)</b>							
High-Level Input Voltage	V <sub>IH1</sub>	(DIN_, PCLKIN, PWDN, MS/CNTL0, CDS/CNTL3, HIM)	0.65 x V <sub>IOVDD</sub>			V	
		SD, SCK, WS	0.7 x V <sub>IOVDD</sub>				
Low-Level Input Voltage	V <sub>IL1</sub>				0.35 x V <sub>IOVDD</sub>	V	
Input Current	I <sub>IN1</sub>	V <sub>IN</sub> = 0V to V <sub>IOVDD</sub>	-20		+20	μA	
<b>THREE-LEVEL LOGIC INPUTS (CONF0, CONF1, CONF2, CONF3, BWS)</b>							
High-Level Input Voltage	V <sub>IH</sub>		0.7 x V <sub>IOVDD</sub>			V	
Low-Level Input Voltage	V <sub>IL</sub>				0.3 x V <sub>IOVDD</sub>	V	
Mid-Level Input Current	I <sub>INM</sub>	(Note 4)	-10		+10	μA	
Input Current	I <sub>IN</sub>		-150		+150	μA	
<b>SINGLE-ENDED OUTPUT (GPO)</b>							
High-Level Output Voltage	V <sub>OH1</sub>	I <sub>OUT</sub> = -2mA	V <sub>IOVDD</sub> - 0.2			V	
Low-Level Output Voltage	V <sub>OL1</sub>	I <sub>OUT</sub> = 2mA			0.2	V	
OUTPUT Short-Circuit Current	I <sub>OS</sub>	V <sub>O</sub> = 0V	V <sub>IOVDD</sub> = 3.0V to 3.6V	16	35	64	mA
			V <sub>IOVDD</sub> = 1.7V to 1.9V	3	12	21	



## DC Electrical Characteristics (continued)

( $V_{AVDD} = V_{DVDD} = 1.7V$  to  $1.9V$ ,  $V_{IOVDD} = 1.7V$  to  $3.6V$ ,  $R_L = 100\Omega \pm 1\%$  (differential), EP connected to PCB ground (GND),  $T_A = -40^\circ C$  to  $+105^\circ C$ , unless otherwise noted. Typical values are at  $V_{AVDD} = V_{DVDD} = V_{IOVDD} = 1.8V$ ,  $T_A = +25^\circ C$ .) (Note 3)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
<b>OPEN-DRAIN INPUT/OUTPUT (RX/SDA, TX/SCL, LFLT)</b>							
High-Level Input Voltage	$V_{IH2}$			0.7 x $V_{IOVDD}$			V
Low-Level Input Voltage	$V_{IL2}$					0.3 x $V_{IOVDD}$	V
Input Current	$I_{IN2}$	(Note 5)	RX/SDA, TX/SCL	-110		+5	$\mu A$
			LFLT	-80		+5	
Low-Level Output Voltage	$V_{OL2}$	$I_{OUT} = 3mA$	$V_{IOVDD} = 1.7V$ to $1.9V$			0.4	V
			$V_{IOVDD} = 3.0V$ to $3.6V$			0.3	
Input Capacitance	$C_{IN}$	Each pin (Note 6)				10	pF
<b>DIFFERENTIAL SERIAL OUTPUT (OUT+, OUT-)</b>							
Differential Output Voltage	$V_{OD}$	Preemphasis off (Figure 1)		300	400	500	mV
		3.3dB Preemphasis setting (Figure 2)		350		610	
		3.3dB Deemphasis setting (Figure 2)		240		425	
Change in $V_{OD}$ Between Complimentary Output States	$DV_{OD}$	Preemphasis off, deemphasis only				25	mV
Output Offset Voltage ( $V_{OUT+} + V_{OUT-})/2 = V_{OS}$	$V_{OS}$	Preemphasis off		1.1	1.4	1.56	V
Change in $V_{OS}$ between Complimentary Output States	$DV_{OS}$					25	mV
Output Short-Circuit Current	$I_{OS}$	$V_{OUT+}$ or $V_{OUT-} = 0V$		-62			mA
		$V_{OUT+}$ or $V_{OUT-} = 1.9V$				25	
Magnitude of Differential Output Short Circuit Current	$I_{OSD}$	$V_{OD} = 0V$				25	mA
Output Termination Resistance (Internal)	$R_O$	From OUT+, OUT- to $V_{AVDD}$		45	54	63	$\Omega$
<b>SINGLE-ENDED SERIAL OUTPUT (OUT+, OUT-)</b>							
Single-Ended Output Voltage	$V_{OUT}$	Preemphasis off, high drive, Figure 3		375	500	625	mV
		3.3dB preemphasis setting, high drive, (Figure 2)		435		765	
		3.3dB deemphasis setting, high drive, (Figure 2)		300		535	
Output Short-Circuit Current	$I_{OS}$	$V_{OUT+}$ or $V_{OUT-} = 0V$		-69			mA
		$V_{OUT+}$ or $V_{OUT-} = 1.9V$				32	
Output Termination Resistance (Internal)	$R_O$	From OUT+ or OUT- to $V_{AVDD}$		45	54	63	$\Omega$
<b>REVERSE CONTROL CHANNEL RECEIVER (OUT+, OUT-)</b>							
High Switching Threshold	$V_{CHR}$	Normal-immunity mode				27	mV
		High-immunity mode				40	

**DC Electrical Characteristics (continued)**

( $V_{AVDD} = V_{DVDD} = 1.7V$  to  $1.9V$ ,  $V_{IOVDD} = 1.7V$  to  $3.6V$ ,  $R_L = 100\Omega \pm 1\%$  (differential), EP connected to PCB ground (GND),  $T_A = -40^\circ C$  to  $+105^\circ C$ , unless otherwise noted. Typical values are at  $V_{AVDD} = V_{DVDD} = V_{IOVDD} = 1.8V$ ,  $T_A = +25^\circ C$ .) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Low Switching Threshold	$V_{CLR}$	Normal-immunity mode	-27			mV	
		High-immunity mode	-40				
<b>LINE FAULT DETECTION INPUT (LMN_)</b>							
Short-to-GND Threshold	$V_{TG}$	Figure 4			0.3	V	
Normal Threshold	$V_{TN}$	Figure 4	0.57		1.07	V	
Open Threshold	$V_{TO}$	Figure 4	1.45		$V_{IO} + 0.06$	V	
Open Input Voltage	$V_{IO}$	Figure 4	1.47		1.75	V	
Short-to-Battery Threshold	$V_{TE}$	Figure 4	2.47			V	
<b>POWER SUPPLY</b>							
Worst-Case Supply Current (Figure 5, Note 7)	$I_{WCS}$	BWS = low	$f_{PCLKIN\_} = 16.6MHz$		96	120	mA
			$f_{PCLKIN\_} = 33.3MHz$		99	125	
			$f_{PCLKIN\_} = 66.6MHz$		111	140	
			$f_{PCLKIN\_} = 104MHz$		134	160	
		BWS = mid	$f_{PCLKIN\_} = 36.6MHz$		102	130	
			$f_{PCLKIN\_} = 104MHz$		133	165	
Sleep Mode Supply Current	$I_{CCS}$	Single wake-up receiver enabled		40	170	$\mu A$	
Power-Down Supply Current	$I_{CCZ}$	$\overline{PWDN} = GND$		5	120	$\mu A$	
<b>ESD PROTECTION</b>							
OUT+, OUT- (Note 8)	$V_{ESD}$	Human body model, $R_D = 1.5k\Omega$ , $C_S = 100pF$			$\pm 8$	kV	
		IEC 61000-4-2, $R_D = 330\Omega$ , $C_S = 150pF$	Contact discharge		$\pm 10$		
			Air discharge		$\pm 12$		
		ISO 10605, $R_D = 2k\Omega$ , $C_S = 330pF$	Contact discharge		$\pm 10$		
Air discharge			$\pm 20$				
All Other Pins (Note 9)	$V_{ESD}$	Human body model, $R_D = 1.5k\Omega$ , $C_S = 100pF$			$\pm 4$	kV	

## AC Electrical Characteristics

( $V_{AVDD} = V_{DVDD} = 1.7V$  to  $1.9V$ ,  $V_{IOVDD} = 1.7V$  to  $3.6V$ ,  $R_L = 100\Omega \pm 1\%$  (differential), EP connected to PCB ground (GND),  $T_A = -40^\circ C$  to  $+105^\circ C$ , unless otherwise noted. Typical values are at  $V_{AVDD} = V_{DVDD} = V_{IOVDD} = 1.8V$ ,  $T_A = +25^\circ C$ .) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>PARALLEL CLOCK INPUT (PCLKIN)</b>						
Clock Frequency	$f_{PCLKIN\_}$	BWS = low, DRS = '1'	8.33		16.66	MHz
		BWS = low, DRS = '0'	16.66		104	
		BWS = mid, DRS = '1'	18.33		52	
		BWS = mid, DRS = '0'	36.66		104	
		BWS = high, DRS = '1'	6.25		12.5	
		BWS = high, DRS = '0'	12.5		78	
Clock Duty Cycle	DC	$t_{high}/t_T$ or $t_{low}/t_T$ (Figure 6), (Note 10)	35	50	65	%
Clock Transition Time	$t_R, t_F$	(Figure 6), (Note 10)			4	ns
Clock Jitter	$t_J$	3.12Gbps bit rate, 300kHz sinusoidal jitter			800	psp-p
<b>I<sup>2</sup>C/UART PORT TIMING</b>						
I <sup>2</sup> C/UART Bit Rate			9.6		1000	kbps
Output Rise Time	$t_R$	30% to 70%, $C_L = 10pF$ to $100pF$ , $1k\Omega$ pullup to IOVDD	20		150	ns
Output Fall Time	$t_F$	70% to 30%, $C_L = 10pF$ to $100pF$ , $1k\Omega$ pullup to IOVDD	20		150	ns
<b>I<sup>2</sup>C TIMING (Figure 7)</b>						
SCL Clock Frequency	$f_{SCL}$	Low $f_{SCL}$ range (I2CMSTBT = 010, I2CSLVSH = 10)	9.6		100	kHz
		Mid $f_{SCL}$ range (I2CMSTBT 101, I2CSLVSH = 01)	> 100		400	kHz
		High $f_{SCL}$ range (I2CMSTBT = 111, I2CSLVSH = 00)	> 400		1000	kHz
START Condition Hold Time	$t_{HD:STA}$	$f_{SCL}$ range	Low		4.0	$\mu s$
			Mid		0.6	
			High		0.26	
Low Period of SCL Clock	$t_{LOW}$	$f_{SCL}$ range	Low		4.7	$\mu s$
			Mid		1.3	
			High	$V_{IOVDD} = 1.7V$ to $< 3V$ (Note 11)	0.6	
				$V_{IOVDD} = 3.0V$ to $3.6V$	0.5	
High Period of SCL Clock	$t_{HIGH}$	$f_{SCL}$ range	Low		4.0	$\mu s$
			Mid		0.6	
			High		0.26	
Repeated START Condition Setup Time	$t_{SU:STA}$	$f_{SCL}$ range	Low		4.7	$\mu s$
			Mid		0.6	
			High		0.26	

**AC Electrical Characteristics (continued)**

( $V_{AVDD} = V_{DVDD} = 1.7V$  to  $1.9V$ ,  $V_{IOVDD} = 1.7V$  to  $3.6V$ ,  $R_L = 100\Omega \pm 1\%$  (differential), EP connected to PCB ground (GND),  $T_A = -40^\circ C$  to  $+105^\circ C$ , unless otherwise noted. Typical values are at  $V_{AVDD} = V_{DVDD} = V_{IOVDD} = 1.8V$ ,  $T_A = +25^\circ C$ .) (Note 3)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Data Hold Time	$t_{HD:DAT}$	$f_{SCL}$ range (Note 10)	Low	0			$\mu s$
			Mid	0			
			High	0			
Data Setup Time	$t_{SU:DAT}$	$f_{SCL}$ range	Low	250			ns
			Mid	100			
			High	50			
Setup Time for Stop Condition	$t_{SU:STO}$	$f_{SCL}$ range	Low	4.0			$\mu s$
			Mid	0.6			
			High	0.26			
Bus Free Time	$t_{BUF}$	$f_{SCL}$ range	Low	4.7			$\mu s$
			Mid	1.3			
			High	0.5			
Data Valid Time (Note 12)	$t_{VD:DAT}$	$f_{SCL}$ range	Low			3.45	$\mu s$
			Mid			0.9	
			High	$V_{IOVDD} = 1.7V$ to $< 3V$ (Note 13)		0.55	
				$V_{IOVDD} = 3.0V$ to $3.6V$		0.45	
Data Valid Acknowledge Time (Note 12)	$t_{VD:ACK}$	$f_{SCL}$ range	Low			3.45	$\mu s$
			Mid			0.9	
			High	$V_{IOVDD} = 1.7V$ to $< 3V$ (Note 14)		0.55	
				$V_{IOVDD} = 3.0V$ to $3.6V$		0.45	
Pulse Width of Spikes Suppressed	$t_{SP}$	$f_{SCL}$ range	Low			50	ns
			Mid			50	
			High			50	
Capacitive Load Each Bus Line	$C_B$	(Note 6)				100	pF
<b>SWITCHING CHARACTERISTICS (Note 10)</b>							
Differential Output Rise/Fall Time	$t_R, t_F$	20% to 80%, $V_{OD} \geq 400mV$ , $R_L = 100\Omega$ , serial bit rate = 3.12Gbps			90	150	ps
Total Serial Output Jitter (Differential Output)	$t_{TSOJ1}$	3.12Gbps PRBS signal, measured at $V_{OD} = 0V$ differential, preemphasis disabled, <a href="#">Figure 8</a>			0.25		UI

## AC Electrical Characteristics (continued)

( $V_{AVDD} = V_{DVDD} = 1.7V$  to  $1.9V$ ,  $V_{IOVDD} = 1.7V$  to  $3.6V$ ,  $R_L = 100\Omega \pm 1\%$  (differential), EP connected to PCB ground (GND),  $T_A = -40^\circ C$  to  $+105^\circ C$ , unless otherwise noted. Typical values are at  $V_{AVDD} = V_{DVDD} = V_{IOVDD} = 1.8V$ ,  $T_A = +25^\circ C$ .) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Deterministic Serial Output Jitter (Differential Output)	$t_{DSOJ2}$	3.12Gbps PRBS signal, measured at $V_{OD} = 0V$ differential, preemphasis disabled (Figure 8)		0.15		UI
Total Serial Output Jitter (Single-ended Output)	$t_{TSOJ1}$	3.12Gbps PRBS signal, measured at $V_O/2$ , preemphasis disabled (Figure 3)		0.25		UI
Deterministic Serial Output Jitter (Single-Ended Output)	$t_{DSOJ2}$	3.12Gbps PRBS signal, measured at $V_O/2$ , preemphasis disabled (Figure 3)		0.15		UI
Parallel Data Input Setup Time	$t_{SET}$	(Figure 9)	2			ns
Parallel Data Input Hold Time	$t_{HOLD}$	(Figure 9)	1			ns
GPI to GPO Delay	$t_{GPIO}$	Deserializer GPI to serializer GPO, (Figure 10)			350	$\mu s$
Serializer Delay (Note 15)	$t_{SD}$	Spread spectrum enabled			5440	Bits
		Spread spectrum disabled			1920	
Link Start Time	$t_{LOCK}$	(Figure 12)			3.5	ms
Power-Up Time	$t_{PU}$	(Figure 13)			8	ms
<b>I<sup>2</sup>S/TDM INPUT TIMING</b>						
WS Frequency	$f_{WS}$	(See Table 3)	8		192	kHz
Sample Word Length	$n_{WS}$	(See Table 3)	8		32	Bits
SCK Frequency	$f_{SCK}$	$f_{SCK} = f_{WS} \times n_{WS} \times (2 \text{ or } 8)$	$(8 \times 8) \times 2$		$(192 \times 32) \times 8$	kHz
SCK Clock High Time	$t_{HC}$	$V_{SCK} R_{VIH}$ , $t_{SCK} = 1/f_{SCK}$ (Note 6)	$0.35 \times t_{SCK}$			ns
SCK Clock Low Time	$t_{LC}$	$V_{SCK} R_{VIL}$ , $t_{SCK} = 1/f_{SCK}$ (Note 6)	$0.35 \times t_{SCK}$			ns
SD, WS Setup Time	$t_{SET}$	(Note 6) (Figure 14)	2			ns
SD, WS Hold Time	$t_{HOLD}$	(Note 6) (Figure 14)	2			ns

**Note 3:** Limits are 100% production tested at  $T_A = +105^\circ C$ . Limits over the operating temperature range and are guaranteed by design and characterization, unless otherwise noted.

**Note 4:** To provide a midlevel, leave the input open, or, if driven, put driver in high impedance. High-impedance leakage current must be less than  $\pm 10\mu A$ .

**Note 5:**  $I_{IN}$  MIN due to voltage drop across the internal pullup resistor.

**Note 6:** Not production tested. Guaranteed by design

**Note 7:** HDCP not enabled (MAX9279 only). See Table 21 for additional supply current when HDCP is enabled.

**Note 8:** Specified pin to ground.

**Note 9:** Specified pin to all supply/ground.

**Note 10:** Not production tested. Guaranteed by design and characterization.

**Note 11:** The I<sup>2</sup>C bus standard  $t_{LOW}$  min =  $0.5\mu s$ .

**Note 12:** I<sup>2</sup>C valid times apply only when the device is operating as a local-side device.

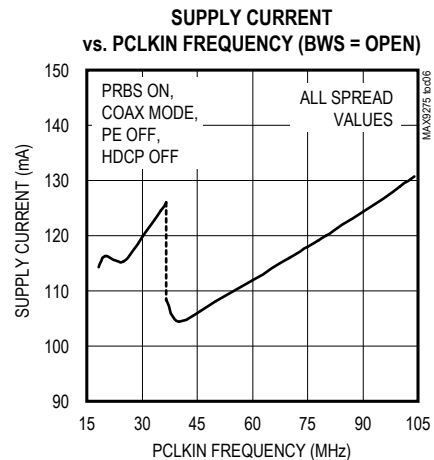
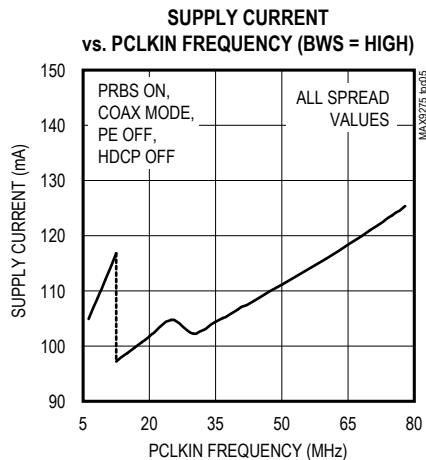
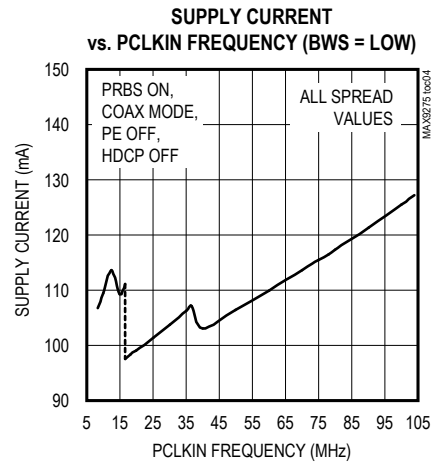
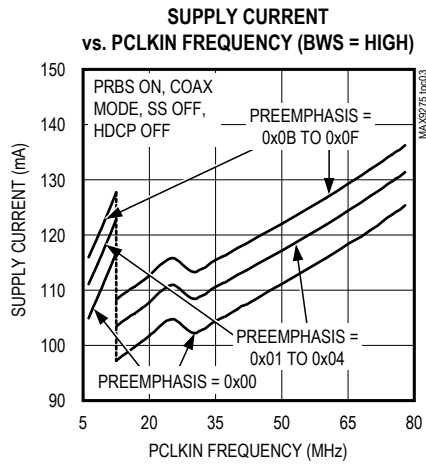
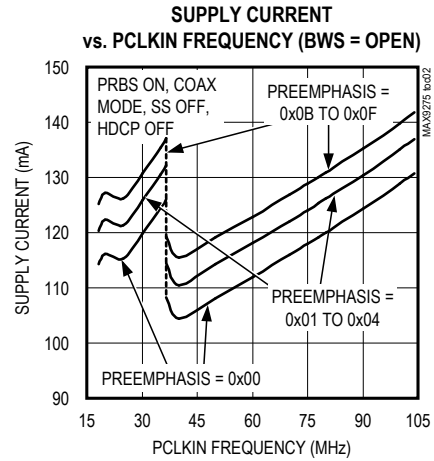
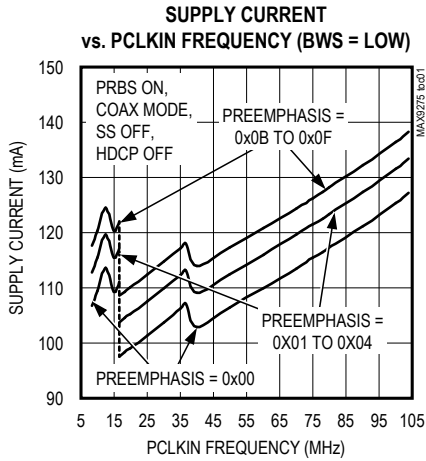
**Note 13:** The I<sup>2</sup>C bus standard  $t_{VD:DAT}$  max =  $0.45\mu s$ .

**Note 14:** The I<sup>2</sup>C bus standard  $t_{VD:ACK}$  max =  $0.45\mu s$ .

**Note 15:** Measured in serial link bit times. Bit time =  $1 / (30 \times f_{PCLKIN})$  for BWS = '0' or open. Bit time =  $1 / (40 \times f_{PCLKIN})$  for BWS = '1'.

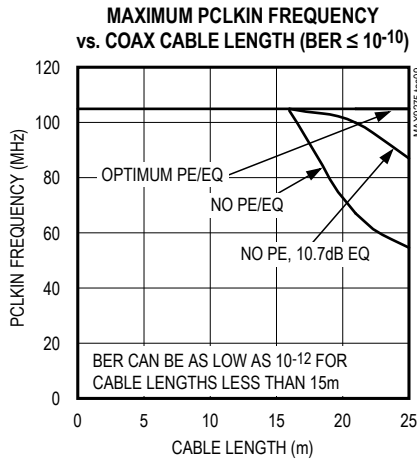
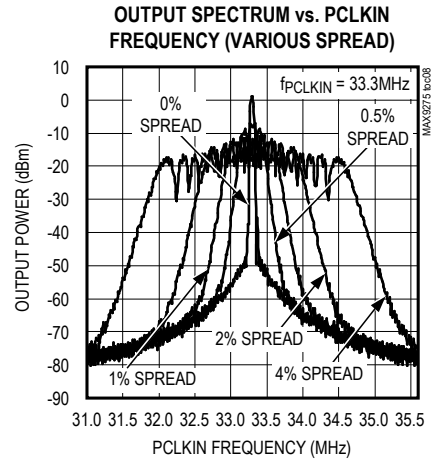
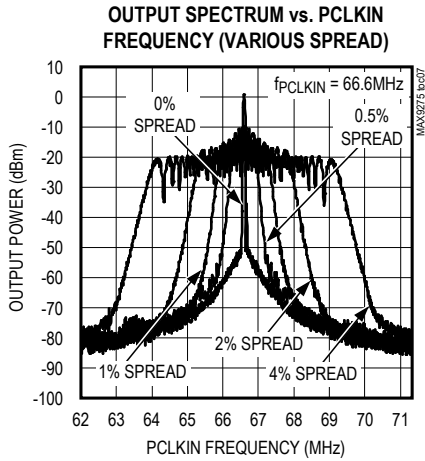
Typical Operating Characteristics

( $V_{AVDD} = V_{DVDD} = V_{IOVDD} = 1.8V$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

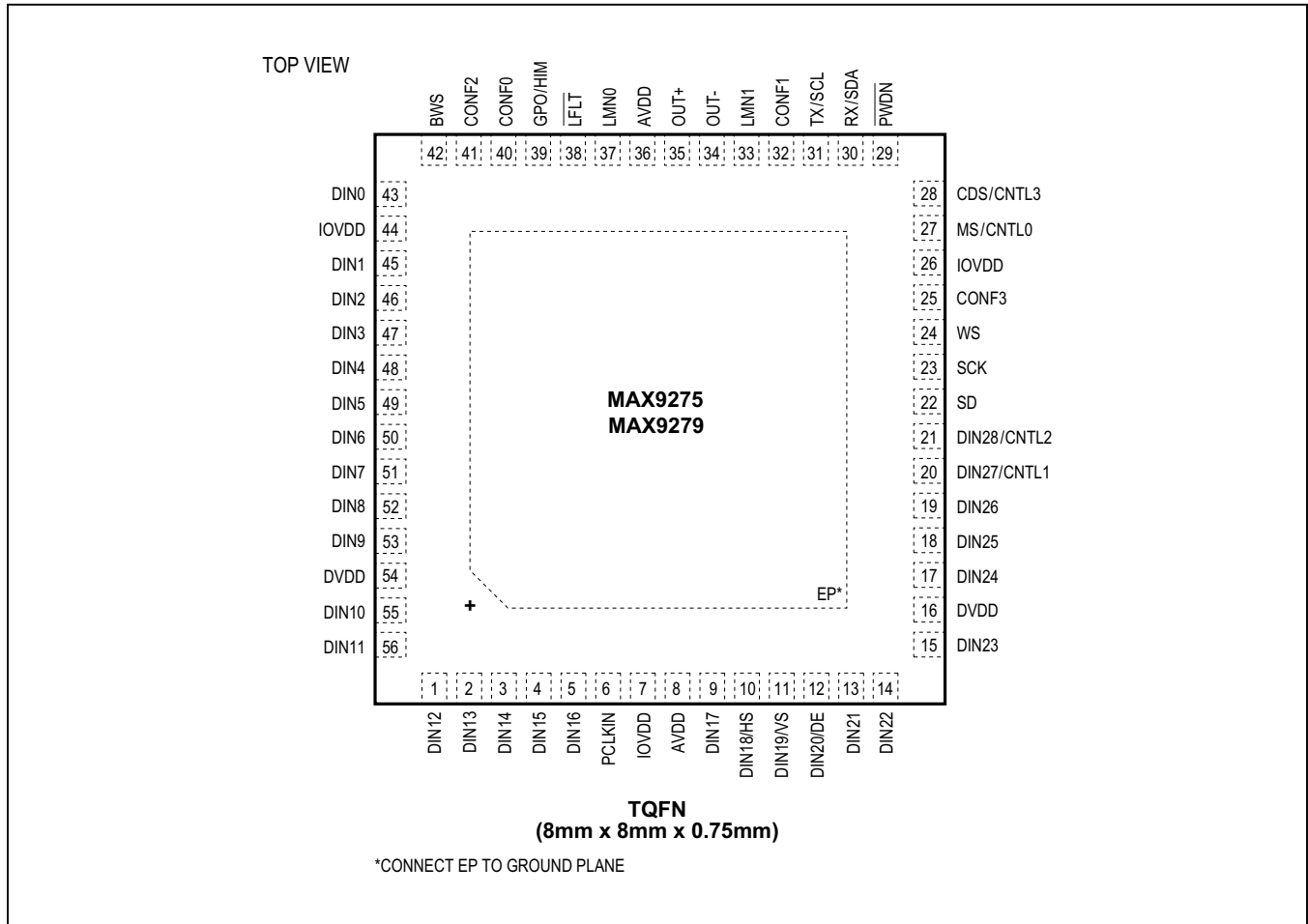


Typical Operating Characteristics (continued)

( $V_{AVDD} = V_{DVDD} = V_{IOVDD} = 1.8V$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)



Pin Configuration



Pin Description

PIN	NAME	FUNCTION
1–5, 9, 43, 45–53, 55, 56	DIN[17:0]	Parallel Data Inputs with Internal Pulldown to EP. Encrypted when HDCP is enabled (MAX9279 only).
6	PCLKIN	Parallel Clock Input with Internal Pulldown to EP. Latches parallel data inputs and provides the PLL reference clock.
7, 26, 44	IOVDD	I/O Supply Voltage. 1.8V to 3.3V logic I/O power supply. Bypass IOVDD to EP with 0.1µF and 0.001µF capacitors as close as possible to the device with the smallest value capacitor closest to IOVDD.
8, 36	AVDD	1.8V Analog Power Supply. Bypass AVDD to EP with 0.1µF and 0.001µF capacitors as close as possible to the device with the smaller capacitor closest to AVDD.
10	DIN18/HS	Parallel Data Input/Horizontal Sync with Internal Pulldown to EP. Defaults to parallel data input on power-up. Horizontal sync input when HDCP is enabled (MAX9279 only) or when in high-bandwidth mode (BWS = open).



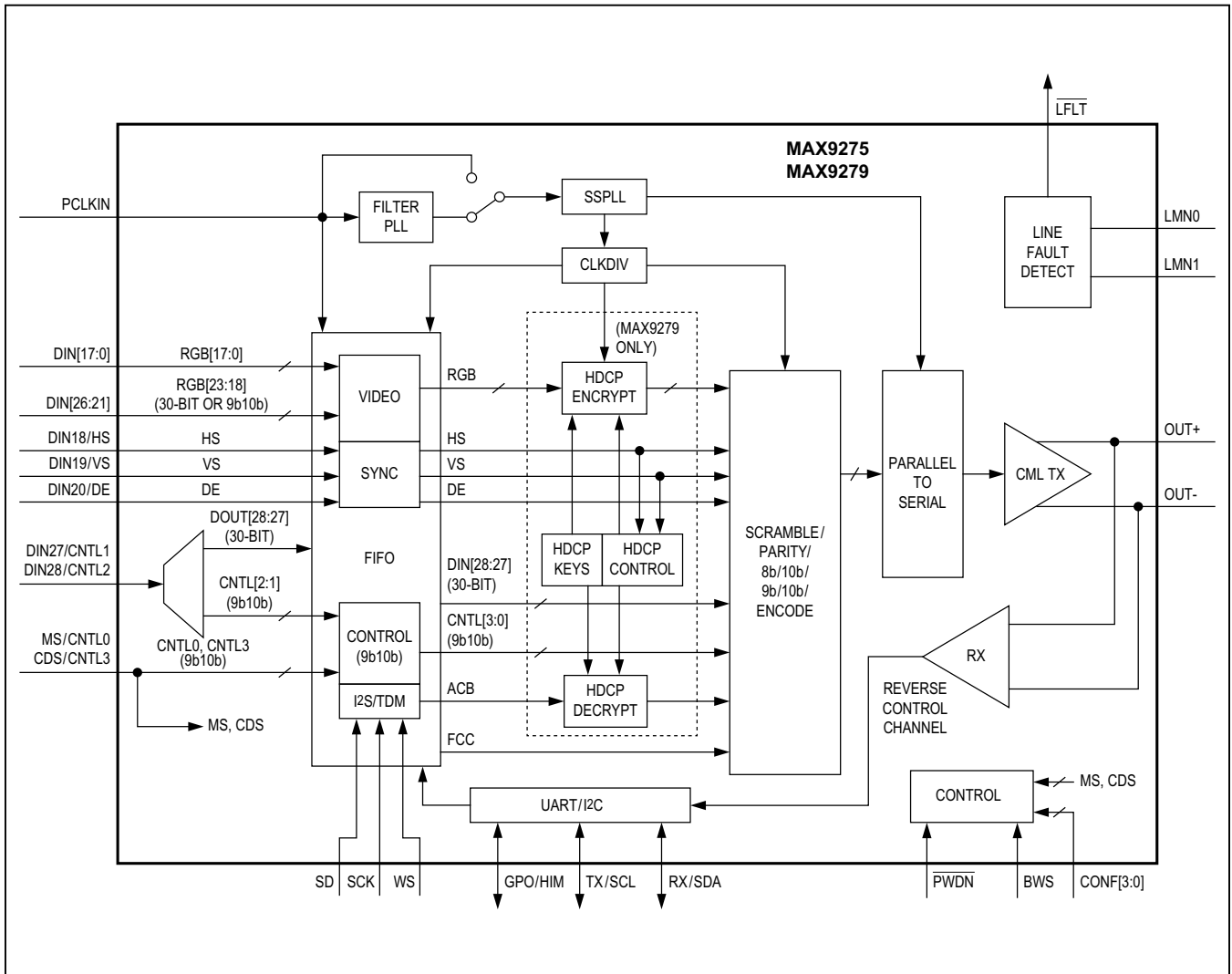
## Pin Description (continued)

PIN	NAME	FUNCTION
11	DIN19/VS	Parallel Data Input/Vertical Sync with Internal Pulldown to EP. Defaults to parallel data input on power-up. Vertical sync input when HDCP is enabled (MAX9279 only) or when in high-bandwidth mode (BWS = open).
12	DIN20/DE	Parallel Data Input/Device Enable with Internal Pulldown to EP. Defaults to parallel data input on power-up. Device enable input when HDCP is enabled (MAX9279 only) or when in high-bandwidth mode (BWS = open).
13–15, 17–19	DIN[26:21]	Parallel Data Inputs with Internal Pulldown to EP. Encrypted when HDCP is enabled (MAX9279 only). DIN[26:21] used only in 32-bit and high-bandwidth modes (BWS = high or open).
16, 54	DVDD	1.8V Digital Power Supply. Bypass DVDD to EP with 0.1 $\mu$ F and 0.001 $\mu$ F capacitors as close as possible to the device with the smaller value capacitor closest to DVDD.
20	DIN27/CNTL1	Parallel Data/Auxiliary Control Signal Input with Internal Pulldown to EP. DIN27 used only in 32-bit mode (BWS = high). DIN27 not encrypted when HDCP is enabled (MAX9279 only). CNTL1 used only in high-bandwidth mode (BWS = open). CNTL1 not encrypted when HDCP is enabled (MAX9279 only).
21	DIN28/CNTL2	Parallel Data/Auxiliary Control Signal Input with Internal Pulldown to EP. DIN28 used only in 32-bit mode (BWS = high). DIN28 not encrypted when HDCP is enabled (MAX9279 only). CNTL2 used only in high-bandwidth mode (BWS = open). CNTL2 not encrypted when HDCP is enabled (MAX9279 only).
22	SD	I <sup>2</sup> S/TDM Serial-Data Input with Internal Pulldown to EP. Disable I <sup>2</sup> S/TDM encoding to use SD as an additional control/data input latched on the selected edge of PCLKIN. Encrypted when HDCP is enabled.
23	SCK	I <sup>2</sup> S/TDM Serial-Clock Input with Internal Pulldown to EP
24	WS	I <sup>2</sup> S/TDM Word-Select Input with Internal Pulldown to EP
25	CONF3	Three-Level Configuration Input. See <a href="#">Table 11</a> for details. Use 6k $\Omega$ (max) for pullup to IOVDD/pulldown to GND.
27	MS/CNTL0	Mode Select/Auxiliary Control Signal Input with Internal Pulldown to EP. Function is determined by the MSCNTL0 register bit and defaults to MS on power-up. MS (MSCNTL0 = 0): Set MS = low, to select base mode. Set MS = high to select the bypass mode. CNTL0 (MSCNTL0 = 1): Used only in high-bandwidth mode (BWS = open). CNTL0 not encrypted when HDCP is enabled (MAX9279 only).
28	CDS/CNTL3	Control Direction Selection/Auxiliary Control Signal Input with Internal Pulldown to EP. Function is determined by the CDSCNTL3 register bit and defaults to CDS on power-up. CDS (CDSCNTL3 = 0): Control link direct selection input with internal pulldown to EP. Set CDS = low when the control channel master $\mu$ C is connected at the serializer. Set CDS = high when the control channel master $\mu$ C is connected at the deserializer. CNTL3 (CDSCNTL3 = 1): Used only in high-bandwidth mode (BWS = open). CNTL3 not encrypted when HDCP is enabled (MAX9279 only).

## Pin Description (continued)

PIN	NAME	FUNCTION
29	$\overline{\text{PWDN}}$	Active-Low, Power-Down Input with Internal Pulldown to EP. Set $\overline{\text{PWDN}}$ low to enter power-down mode to reduce power consumption.
30	RX/SDA	UART Receive/I <sup>2</sup> C Serial Data Input/Output with Internal 30k $\Omega$ Pullup to IOVDD. Function is determined by the state of CONF[1:0] at power-up (Table 10). RX/SDA has an open-drain driver and requires a pullup resistor. RX: Input of the serializer's UART. SDA: Data input/output of the serializer's I <sup>2</sup> C master/slave.
31	TX/SCL	UART Transmit/I <sup>2</sup> C Serial Clock Input/Output with Internal 30k $\Omega$ Pullup to IOVDD. Function is determined by the state of CONF[1:0] at power-up (Table 10). TX/SCL has an open-drain driver and requires a pullup resistor. TX: Output of the serializer's UART. SCL: Clock input/output of the serializer's I <sup>2</sup> C master/slave.
32	CONF1	Three-Level Configuration Input. See Table 10 for details. Use 6k $\Omega$ (max) for pullup to IOVDD/pulldown to GND.
33	LMN1	Line-Fault Monitor Input 1 (see Figure 4)
34	OUT-	Inverting CML Coax/Twisted-Pair Serial Output
35	OUT+	Noninverting CML Coax/Twisted-Pair Serial Output
37	LMN0	Line-Fault Monitor Input 0 (see Figure 4)
38	$\overline{\text{LFLT}}$	Active-Low Open-Drain Line-Fault Output. $\overline{\text{LFLT}}$ has a 60k $\Omega$ internal pullup to IOVDD. $\overline{\text{LFLT}}$ = low indicates a line fault. $\overline{\text{LFLT}}$ is output high when $\overline{\text{PWDN}}$ = low.
39	GPO/HIM	General-Purpose Output/High-Immunity Mode Input. Functions as HIM input with internal pulldown to EP at power-up or when resuming from power-down mode ( $\overline{\text{PWDN}}$ = low), and switches to GPO output automatically after power-up. HIM: Default HIGHIMM bit value is latched at power-up or when resuming from power-down mode ( $\overline{\text{PWDN}}$ = low) and is active high. Connect HIM to IOVDD with a 30k $\Omega$ or less pullup resistor to set high or leave open to set low. HIGHIMM can be programmed to a different value after power-up. HIGHIMM in the deserializer must be set to the same value. GPO: Output follows the state of the GPI (or INT) input on the deserializer. GPO is low after power-up or when $\overline{\text{PWDN}}$ is low.
40	CONF0	Three-Level Configuration Input. The state of CONF0 latches at power-up or when resuming from power-down mode ( $\overline{\text{PWDN}}$ = low). See Table 10 for details. Use 6k $\Omega$ (max) for pullup to IOVDD/pulldown to GND.
41	CONF2	Three-Level Configuration Input. The state of CONF2 latches at power-up or when resuming from power-down mode ( $\overline{\text{PWDN}}$ = low). See Table 11 for details. Use 6k $\Omega$ (max) for pullup to IOVDD/pulldown to GND.
42	BWS	Three-Level Bus Width Select Input. Set BWS to the same level on both sides of the serial link. Set BWS = low with 6k $\Omega$ (max) pulldown for 24 bit mode. Set BWS = 6k $\Omega$ (max) pullup to IOVDD high for 32-bit mode. Set BWS = open for high-bandwidth mode.
—	EP	Exposed Pad. EP is internally connected to device ground. <b>must</b> connect EP to the PCB ground plane through an array of vias for proper thermal and electrical performance.

Functional Diagram



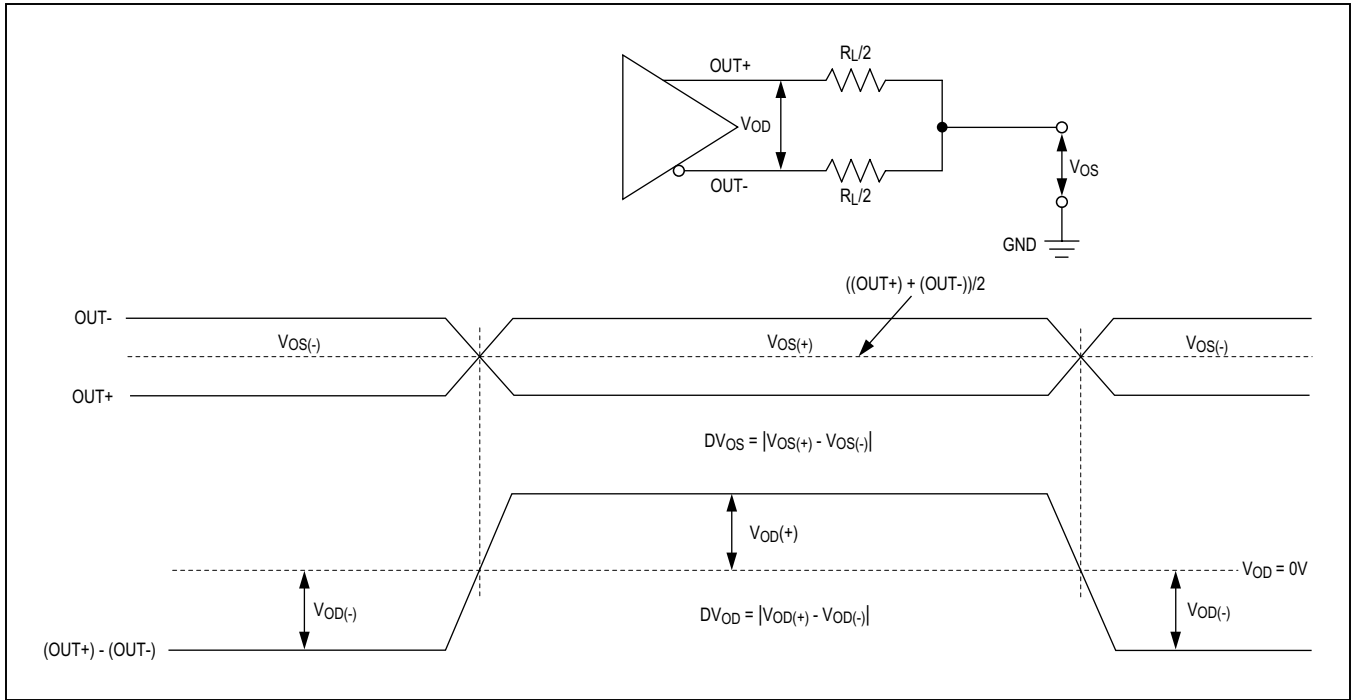


Figure 1. Serial-Output Parameters

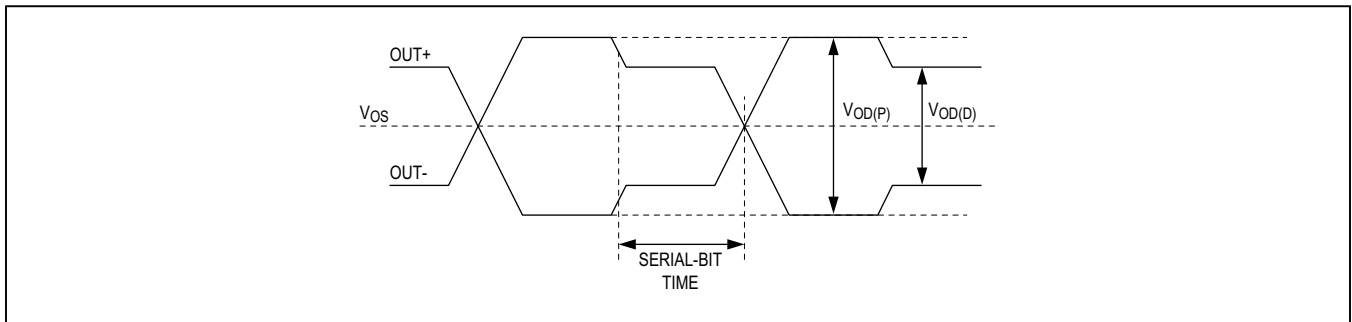


Figure 2. Output Waveforms at OUT+, OUT-

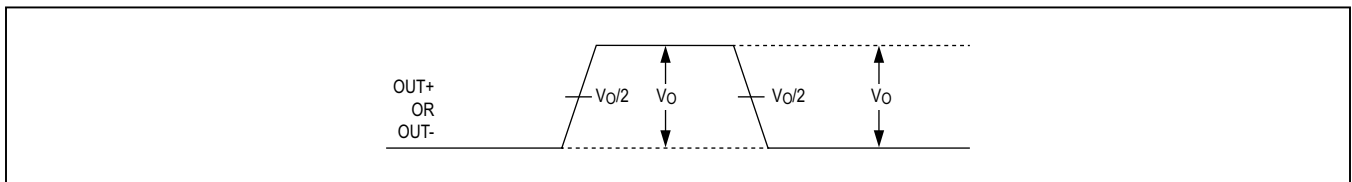


Figure 3. Single-Ended Output Template

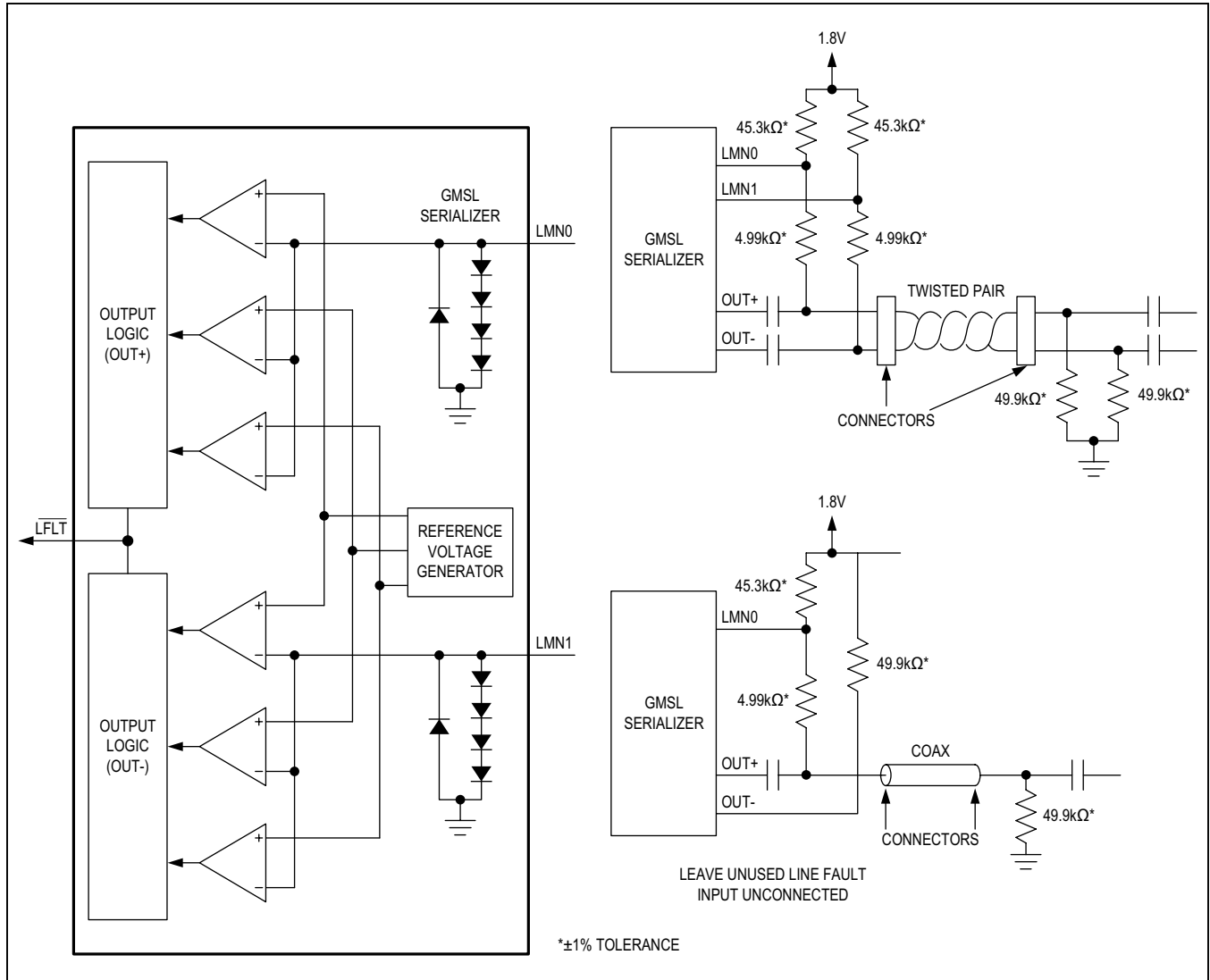


Figure 4. Line Fault Detector Circuit

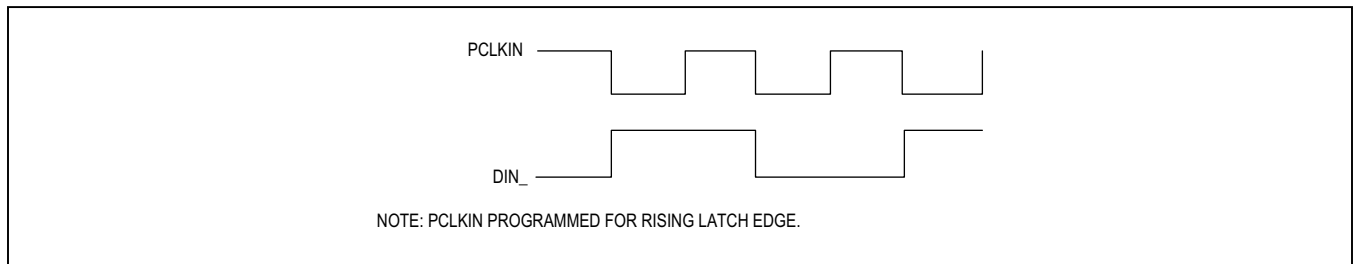


Figure 5. Worst-Case Pattern Input

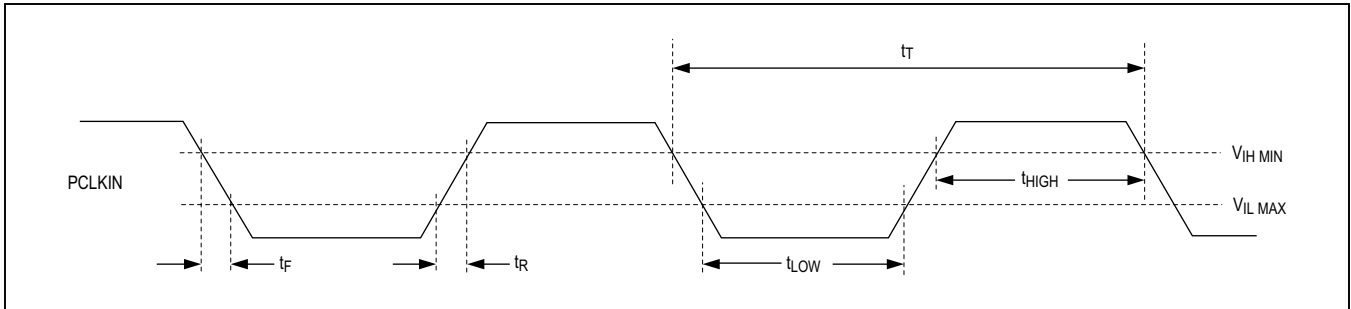


Figure 6. Parallel Clock Input Requirements

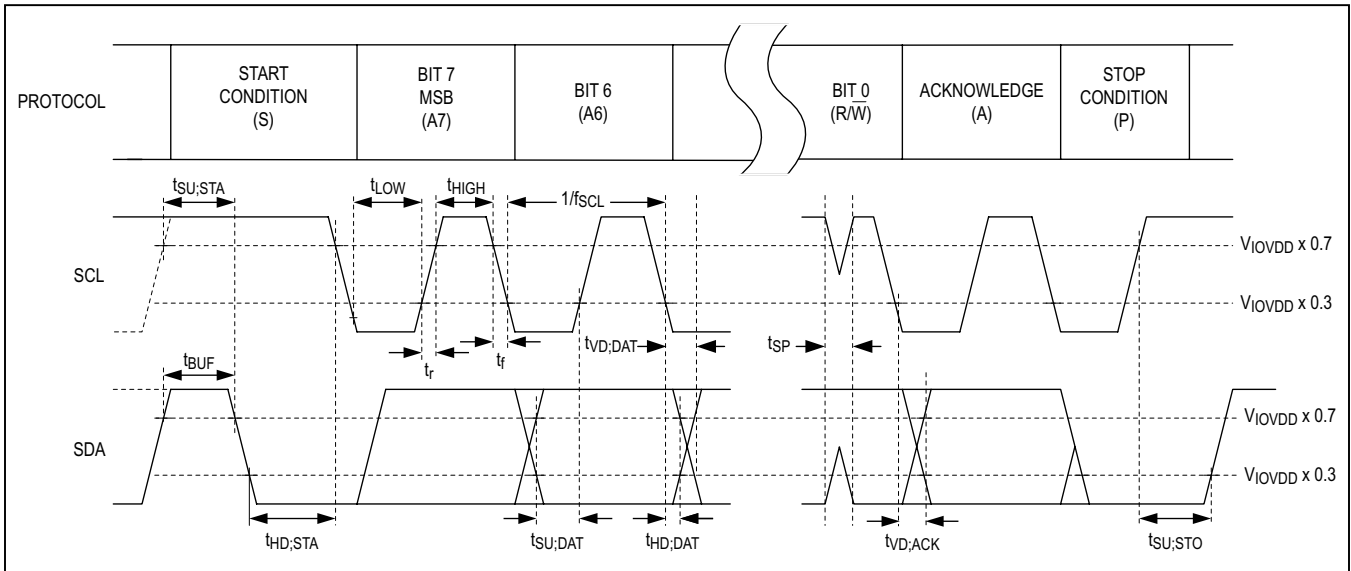


Figure 7. I<sup>2</sup>C Timing Parameters

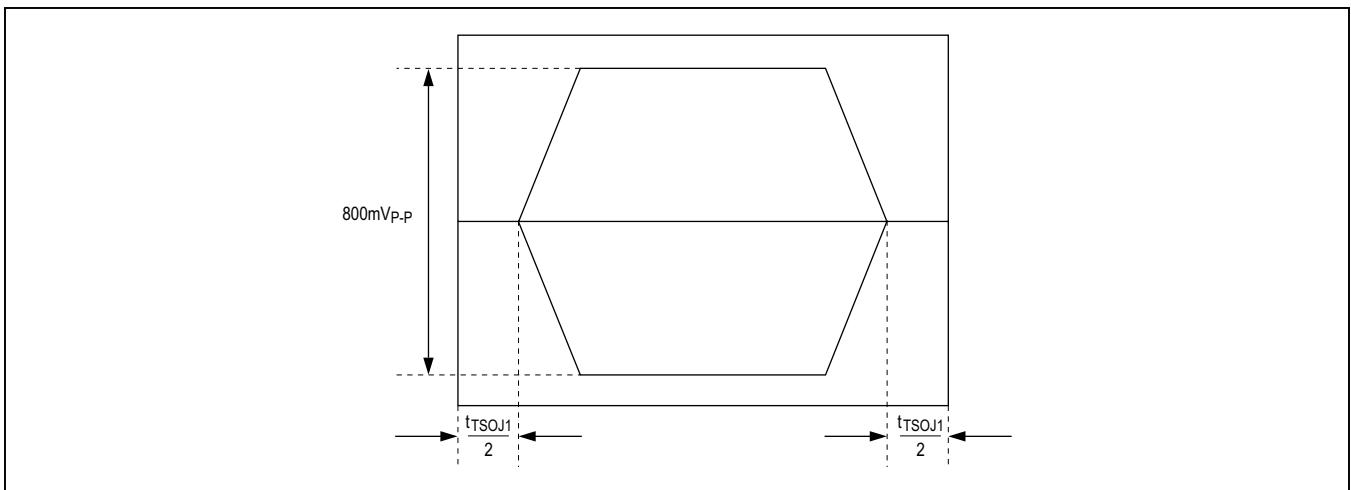


Figure 8. Differential Output Template

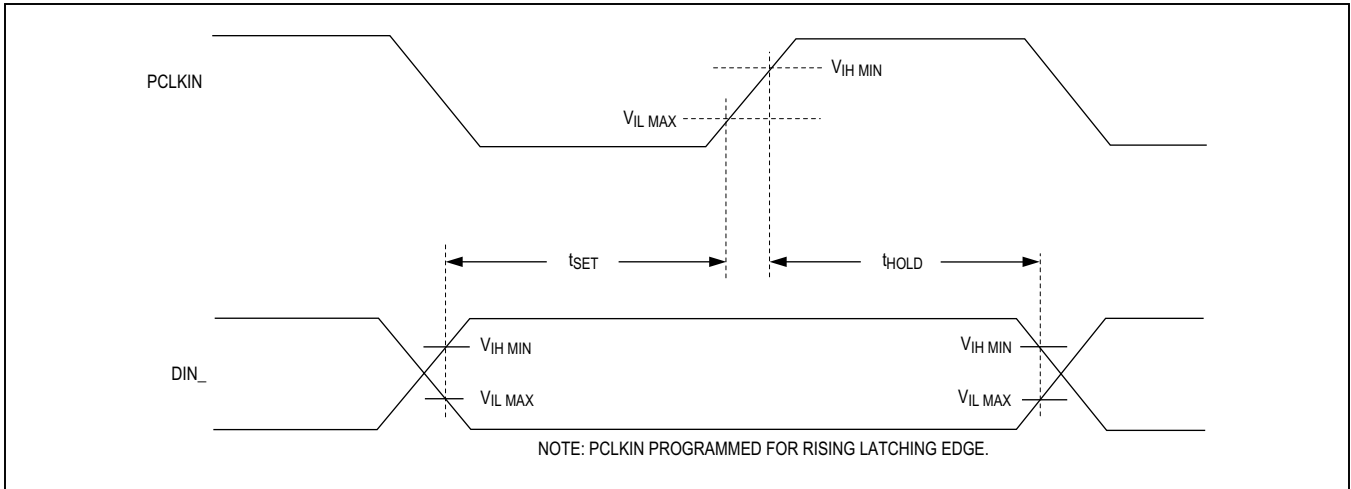


Figure 9. Input Setup and Hold Times

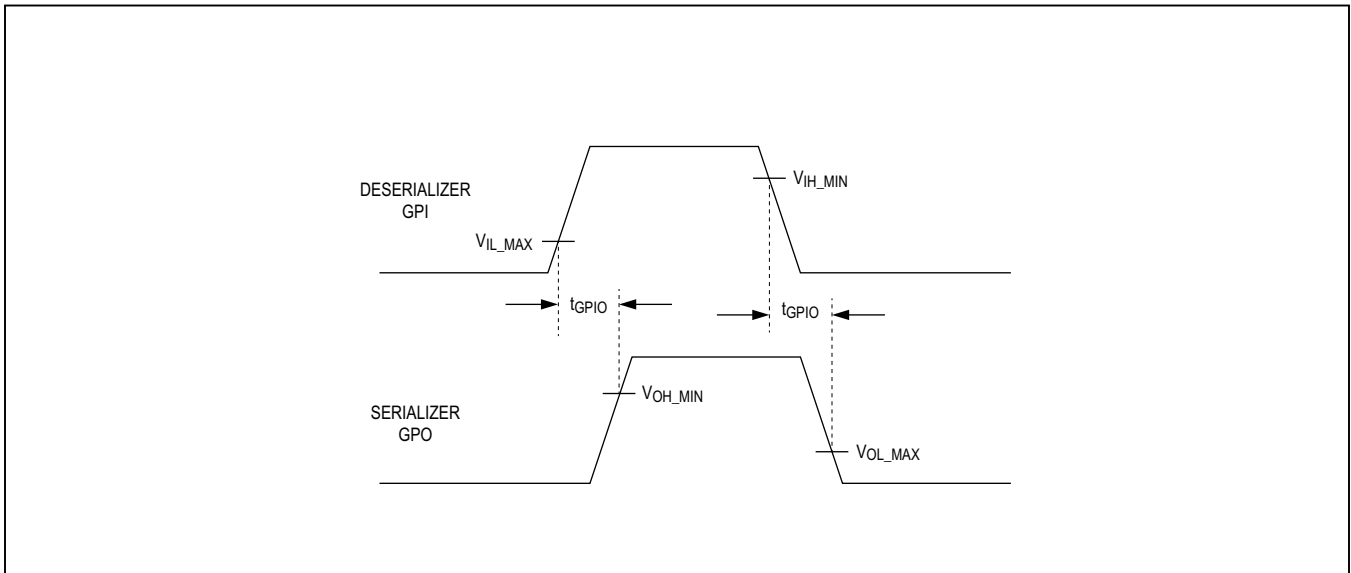


Figure 10. GPI-to-GPO Delay

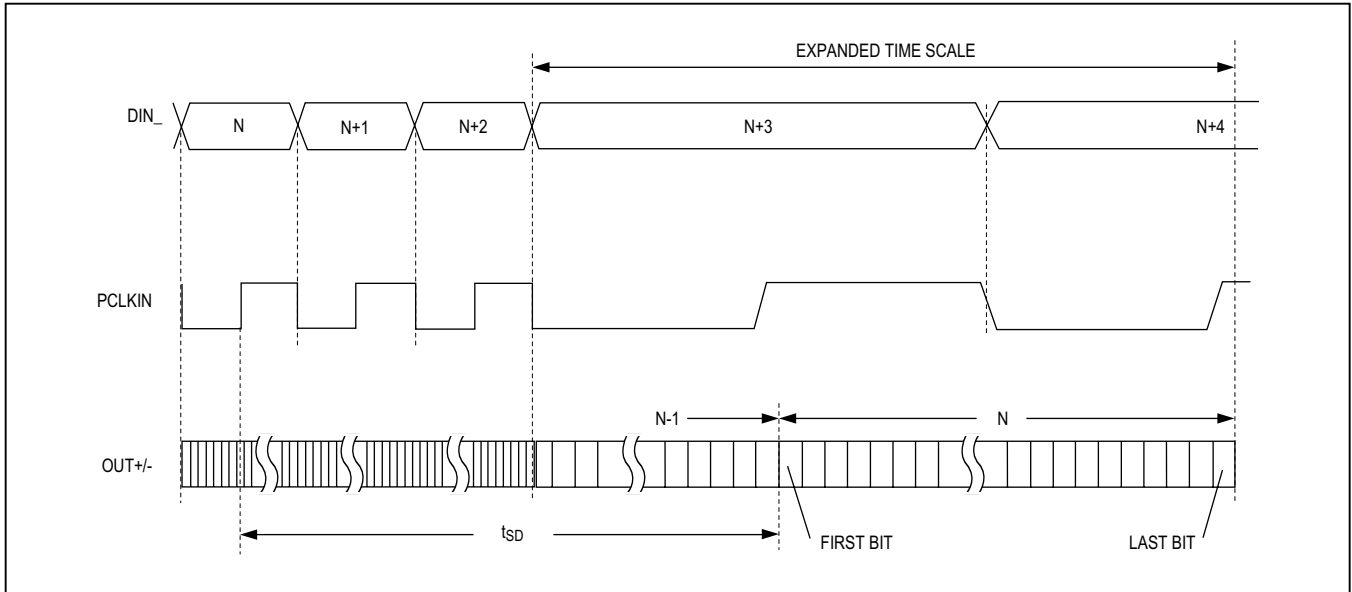


Figure 11. Serializer Delay

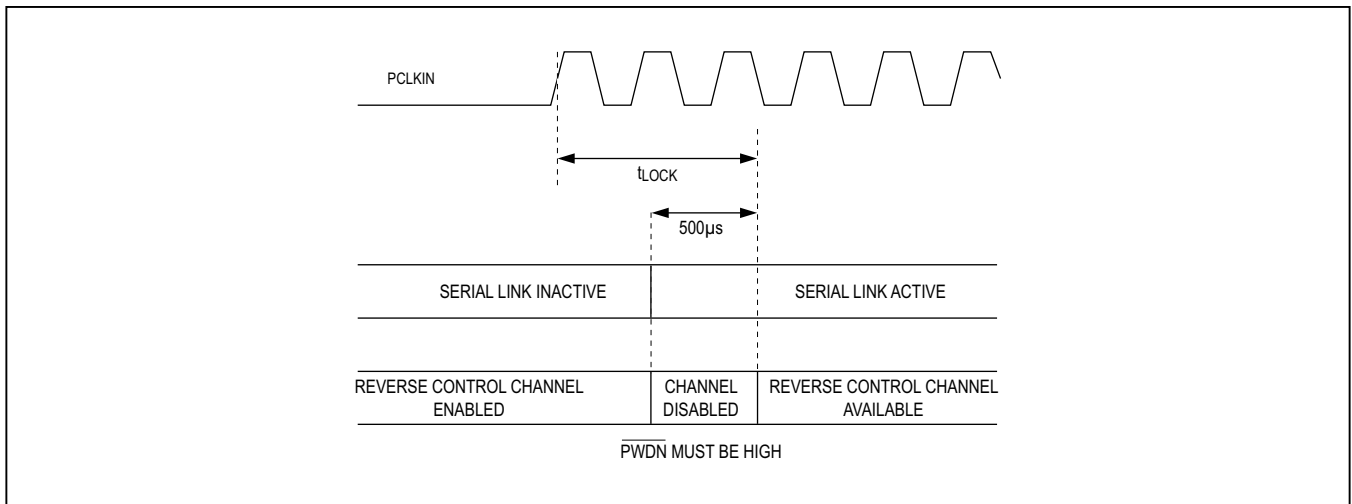


Figure 12. Link Startup Time



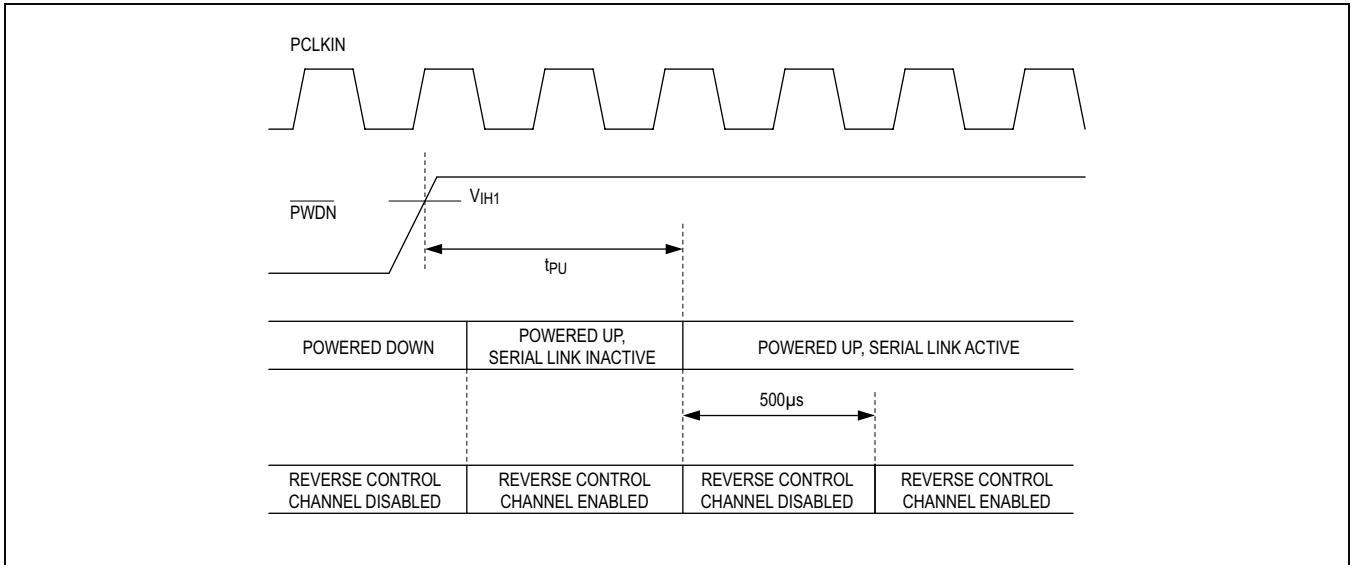


Figure 13. Power-Up Delay

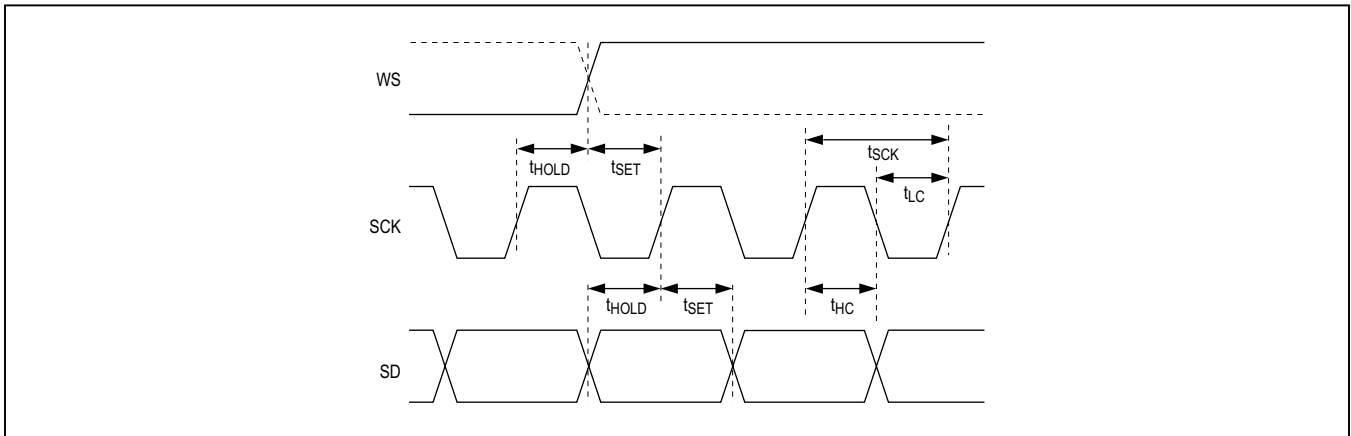


Figure 14. Input I<sup>2</sup>S Timing Parameters

## Detailed Description

The MAX9275/MAX9279 serializers, when paired with the MAX9276/MAX9280 deserializers, provides the full set of operating features, but is backward compatible with the MAX9249–MAX9270 family of Gigabit Multimedia Serial Link (GMSL) devices, and have basic functionality when paired with any GMSL device. The MAX9279 has High-Bandwidth Digital Content Protection (HDCP) while the MAX9275 does not.

The serializer has a maximum serial-bit rate of 3.12Gbps for up to 15m of cable and operates up to a maximum output clock of 104MHz in 24-bit mode and 27-bit high-bandwidth mode, or 78MHz in 32-bit mode. This bit rate and output flexibility support a wide range of displays, from QVGA (320 x 240) to 1920 x 720 and higher with 24-bit color, as well as megapixel image sensors. An encoded audio channel supports L-PCM I<sup>2</sup>S stereo and up to eight channels of L-PCM in TDM mode. Sample rates of 32kHz to 192kHz are supported with sample depth from 8 to 32 bits. Output pre/deemphasis, combined with GMSL deserializer equalization, extends the cable length and enhances link reliability.

The control channel enables a  $\mu$ C to program the serializer and deserializer registers and program registers

on peripherals. The control channel is also used to perform HDCP functions (MAX9279 only). The  $\mu$ C can be located at either end of the link, or when using two  $\mu$ Cs, at both ends. Two modes of control-channel operation are available. Base mode uses either I<sup>2</sup>C or GMSL UART protocol, while bypass mode uses a user-defined UART protocol. UART protocol allows full-duplex communication, while I<sup>2</sup>C allows half-duplex communication.

Spread spectrum is available to reduce EMI on the serial output. The serial output complies with ISO 10605 and IEC 61000-4-2 ESD protection standards.

## Register Mapping

Registers set the operating conditions of the serializers and are programmed using the control channel in base mode. The MAX9275/MAX9279 holds its own device address and the device address of the deserializer it is paired with. Similarly, the deserializer holds its own device address and the address of the MAX9275/MAX9279. Whenever a device address is changed, be sure to write the new address to both devices. The default device address of the serializer is 0x80. Registers 0x00 and 0x01 in both devices hold the device addresses.

**Table 1. Input Map**

SIGNAL	INPUT PIN	MODE		
		24-BIT MODE (BWS = LOW)	HIGH-BANDWIDTH MODE (BWS = MID)	32-BIT MODE (BWS = HIGH)
R[5:0]	DIN[5:0]	Used	Used	Used
G[5:0]	DIN[11:6]	Used	Used	Used
B[5:0]	DIN[17:12]	Used	Used	Used
HS, VS, DE	DIN18/HS, DIN19/VS, DIN20/DE	Used**	Used**	Used**
R[7:6]	DIN[22:21]	Not used	Used	Used
G[7:6]	DIN[24:23]	Not used	Used	Used
B[7:6]	DIN[26:25]	Not used	Used	Used
CNTL[2:1]	DIN[28:27]/CNTL[2:1]	Not used	Used*, **	Used**
CNTL3, CNTL0	CDS/CNTL3, MS/CNTL0	Not used	Used*, **	Not used
I <sup>2</sup> S/TDM	WS, SCK, SD	Used	Used	Used
AUX SIGNAL		Used	Used	Used

\*See the [High-Bandwidth Mode](#) section for details on timing requirements.

\*\*Not encrypted when HDCP is enabled (MAX9279 only).